CM Questionnaire

**PROJECT INFORMATION**

* + Company:
  + Contact person:
  + Product name:
  + RFQ quantity(ies):
  + Number of production batches:
  + Desired Date of Delivery:
  + Urgency (high-normal-low):
  + Future production batches planned?:

**DESIRED MIKROELEKTRONIKA SERVICES**

* + Electronics design (YES/NO):
  + PCB design (YES/NO):
  + BOM components procurement (YES/NO):
  + PCB production/procurement (YES/NO):
  + Assembly/board manufacturing (YES/NO):
  + Testing (YES/NO):
  + Package (cardbox) creation (YES/NO):

**ADMINISTRATIVE**

* + Bill-To address
    - Company Name:
    - Contact Person:
    - Phone number:
  + Ship-To address
    - Company Name:
    - Contact Person:
    - Address:
    - Phone number:

**BOM COMPONENTS SPECIFICATION**

* + Are there any critical components?

(if yes, please specify in BOM which)

* + Are there any components with unusual reflow profiles?
  + Are there any obsolete components?
  + Are there any hard-to-find components?
  + Can we suggest uncritical components replacements (e.g. Headers)?

**PCB SPECIFICATION**

* + PCB thickness [mm]:
  + board material:
  + number of layers:
  + layer stackup:
  + surface finish:
* finished cooper:
  + solder mask:
  + legend/silk:
  + board size:
  + panelized (yes/no):

**TESTING/PROGRAMMING**

* Prototype already available?
* Testing/programming procedure already available?
* Estimated testing/programming time per board:
* Testing equipment list:

**ADDITIONAL REMARKS**